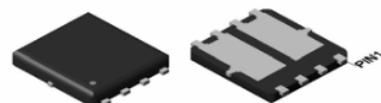


Features

- Dual P-Channel, -5V Logic Level Control
- Enhancement mode
- Very low on-resistance $R_{DS(on)}$ @ $V_{GS}=-4.5$ V
- Fast Switching
- 100% Avalanche test
- Pb-free lead plating; RoHS compliant

V_{DS}	-30	V
$R_{DS(on),TYP} @ V_{GS}=-10$ V	11	mΩ
$R_{DS(on),TYP} @ V_{GS}=-4.5$ V	15	mΩ
I_D	-18	A

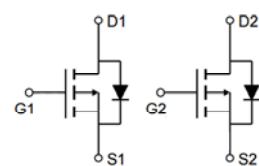
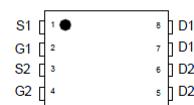
Dual PDFN5x6



Halogen-Free

Part ID	Package Type	Marking	Tape and reel information
VSP011P03MD	PDFN5x6	011P03MD	3000pcs/reel

Top View



Maximum ratings, at $T_j=25$ °C, unless otherwise specified

Symbol	Parameter	Rating	Unit	
$V_{(BR)DSS}$	Drain-Source breakdown voltage	-30	V	
I_s	Diode continuous forward current	$T_c=25$ °C	-18	A
I_D	Continuous drain current@ $V_{GS}=10$ V	$T_c=25$ °C	-18	A
		$T_c=100$ °C	-11.5	A
I_{DM}	Pulse drain current tested ②	$T_c=25$ °C	-70	A
P_d	Maximum power dissipation	$T_c=25$ °C	35	W
V_{GS}	Gate-Source voltage	± 20	V	
T_{STG}	Storage temperature range	-55 to 155	°C	
T_j	Maximum Junction Temperature①	150	°C	

Thermal Characteristics

Symbol	Parameter	Typical	Unit
$R_{\theta JC}$	Thermal Resistance-Junction to Case	3.5	°C/W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	45	°C/W

Drain-Source Avalanche Ratings

EAS	Avalanche Energy, Single Pulsed ③	25	mJ
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Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_D=-250\mu\text{A}$	-30	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current($T_c=25^\circ\text{C}$)	$V_{\text{DS}}=-24\text{V}, V_{\text{GS}}=0\text{V}$	--	--	-1	μA
	Zero Gate Voltage Drain Current($T_c=125^\circ\text{C}$)	$V_{\text{DS}}=-24\text{V}, V_{\text{GS}}=0\text{V}$	--	--	-100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_D=-250\mu\text{A}$	-1.0	-1.6	-2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance②	$V_{\text{GS}}=-10\text{V}, I_D=-10\text{A}$	--	11	13	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance②	$V_{\text{GS}}=-4.5\text{V}, I_D=-10\text{A}$	--	15	18	$\text{m}\Omega$
Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
C_{iss}	Input Capacitance	$V_{\text{DS}}=-15\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	--	1950	--	pF
C_{oss}	Output Capacitance		--	320	--	pF
C_{rss}	Reverse Transfer Capacitance		--	225	--	pF
Q_g	Total Gate Charge	$V_{\text{DS}}=-10\text{V}, I_D=-10\text{A}, V_{\text{GS}}=-10\text{V}$	--	28	--	nC
Q_{gs}	Gate-Source Charge		--	4.5	--	nC
Q_{gd}	Gate-Drain Charge		--	9	--	nC
Switching Characteristics						
$t_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{DD}}=-15\text{V}, I_D=-1\text{A}, R_G=6.8\Omega, V_{\text{GS}}=-10\text{V}$	--	9	--	nS
t_r	Turn-on Rise Time		--	10	--	nS
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time		--	22	--	nS
t_f	Turn-Off Fall Time		--	11	--	nS
Source- Drain Diode Characteristics@ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
V_{SD}	Forward on voltage	$I_{\text{SD}}=-10\text{A}, V_{\text{GS}}=0\text{V}$	--	-0.84	-1.3	V
t_{rr}	Reverse Recovery Time	$T_J=25^\circ\text{C}, I_{\text{SD}}=-8\text{A}, V_{\text{GS}}=0\text{V}$ $dI/dt=-100\text{A}/\mu\text{s}$	--	26	--	nS
Q_{rr}	Reverse Recovery Charge		--	35	--	nC

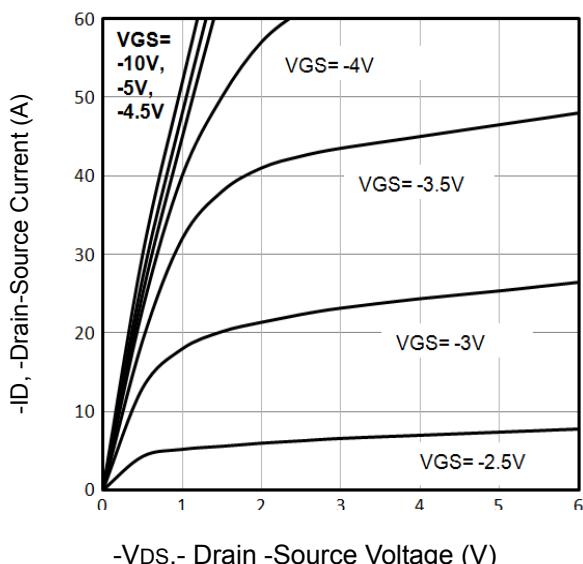
NOTE:

① Repetitive rating; pulse width limited by max. junction temperature.

②Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

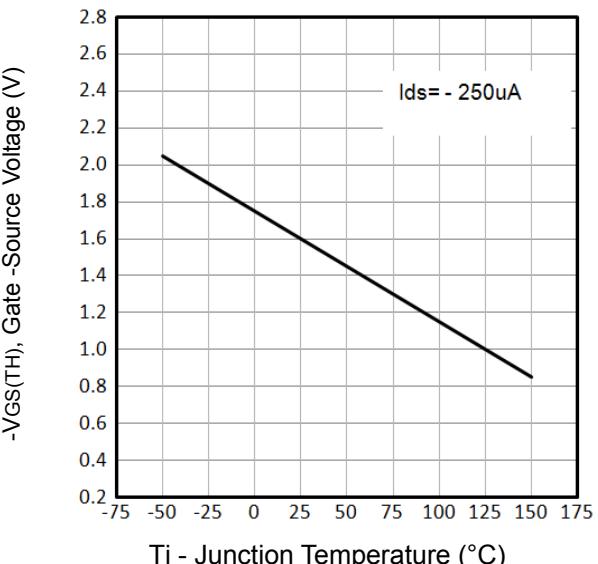
③Limited by $T_{J\text{max}}$, starting $T_J = 25^\circ\text{C}$, $L = 0.5\text{mH}$, $R_G = 25\Omega$, $I_{AS} = -10\text{A}$, $V_{GS} = -10\text{V}$. Part not recommended for use above this value

Typical Characteristics



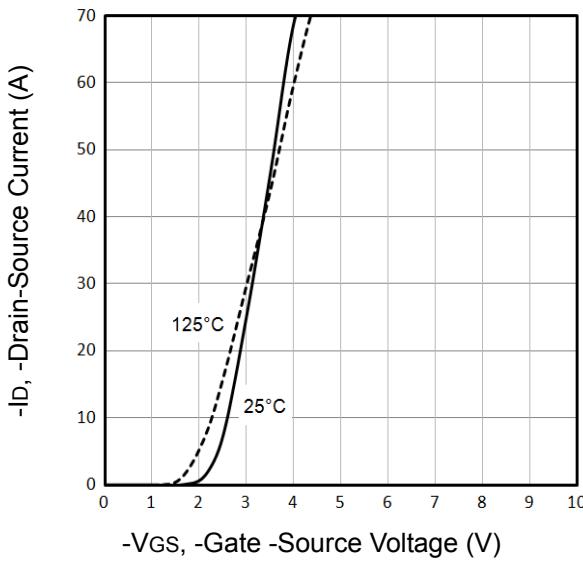
- VDS , - Drain -Source Voltage (V)

Fig1. Typical Output Characteristics



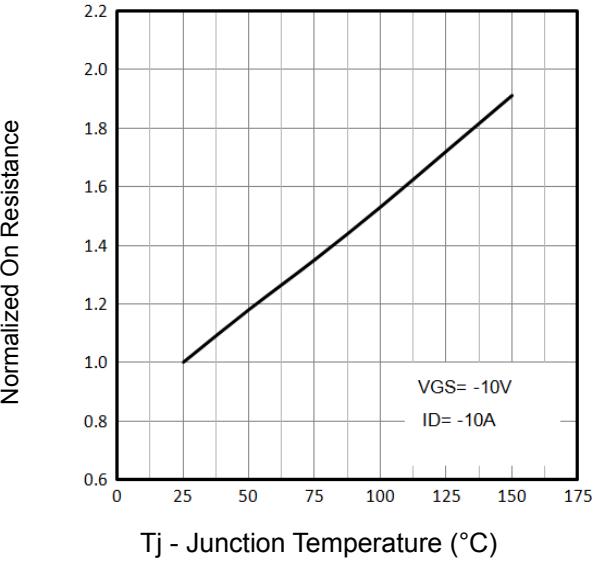
T_j - Junction Temperature (°C)

Fig2. Threshold Voltage Vs. Temperature



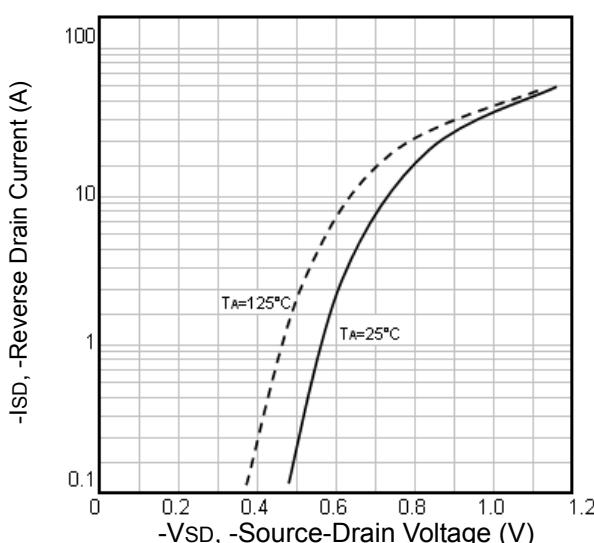
- VGS , -Gate -Source Voltage (V)

Fig3. Typical Transfer Characteristics



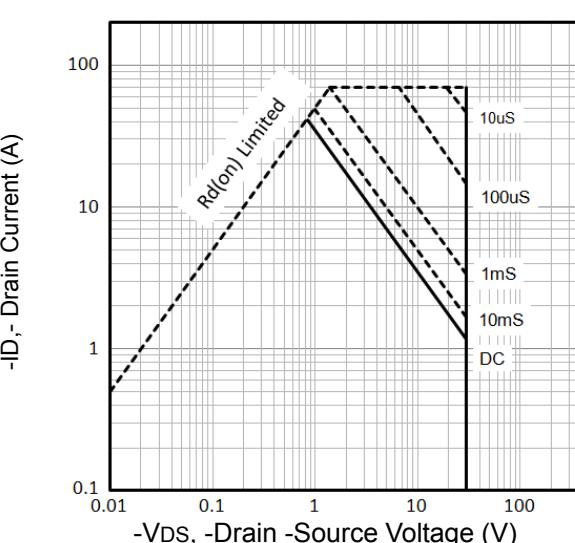
T_j - Junction Temperature (°C)

Fig4. Normalized On-Resistance Vs. Temperature



- VSD , -Source-Drain Voltage (V)

Fig5. Typical Source-Drain Diode Forward Voltage



- VDS , - Drain -Source Voltage (V)

Fig6. Maximum Safe Operating Area

Typical Characteristics

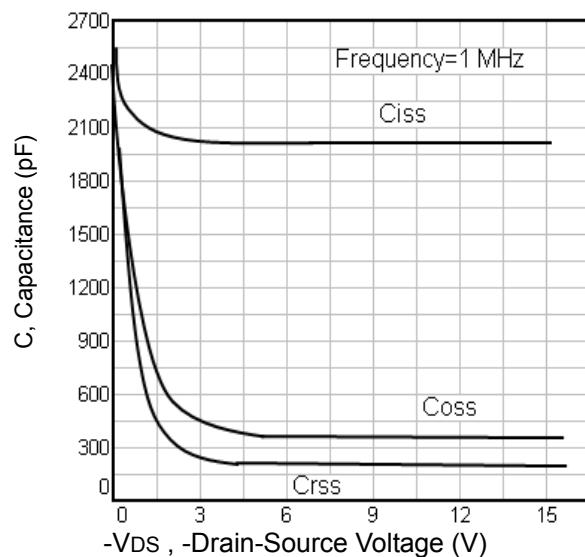


Fig7. Typical Capacitance Vs.Drain-Source Voltage

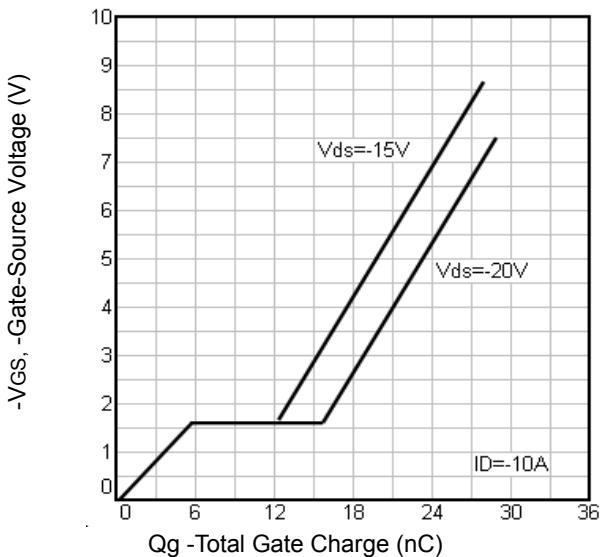


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

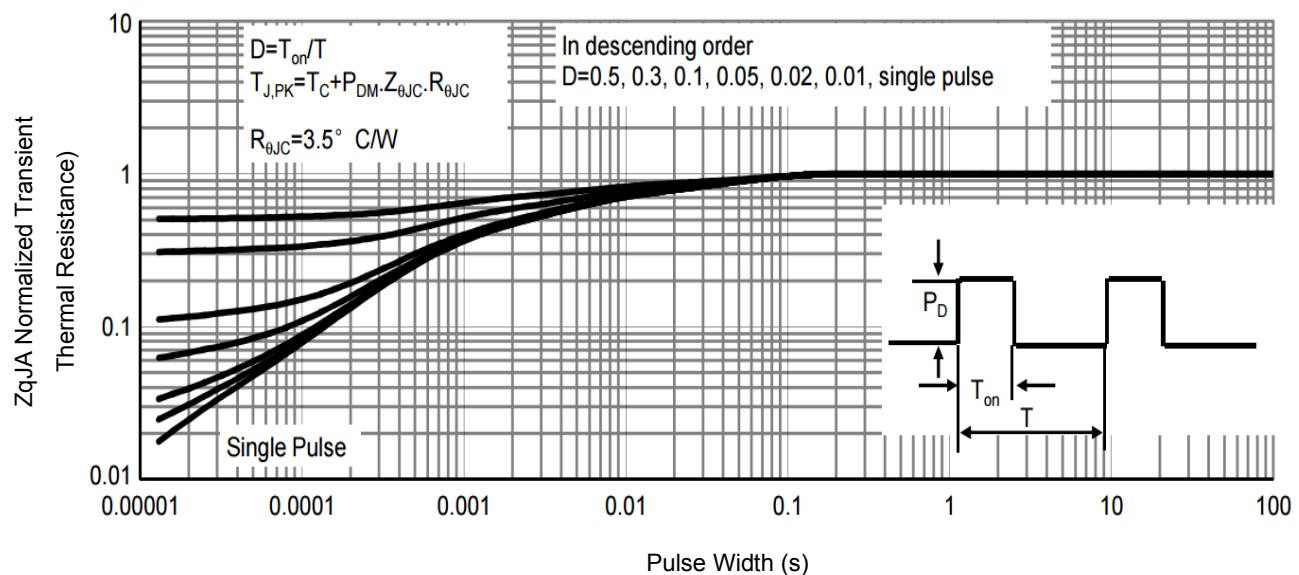


Fig9. Normalized Maximum Transient Thermal Impedance

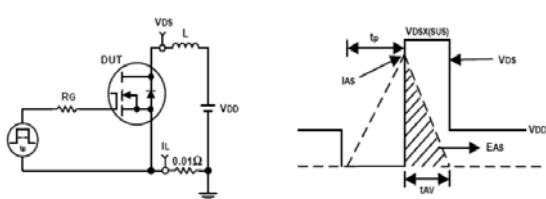


Fig10. Unclamped Inductive Test Circuit and Waveforms

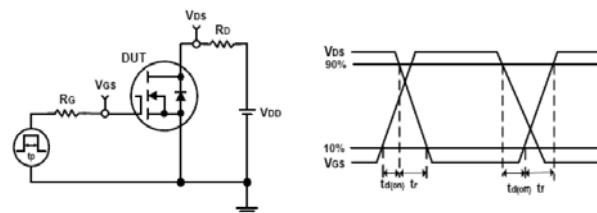
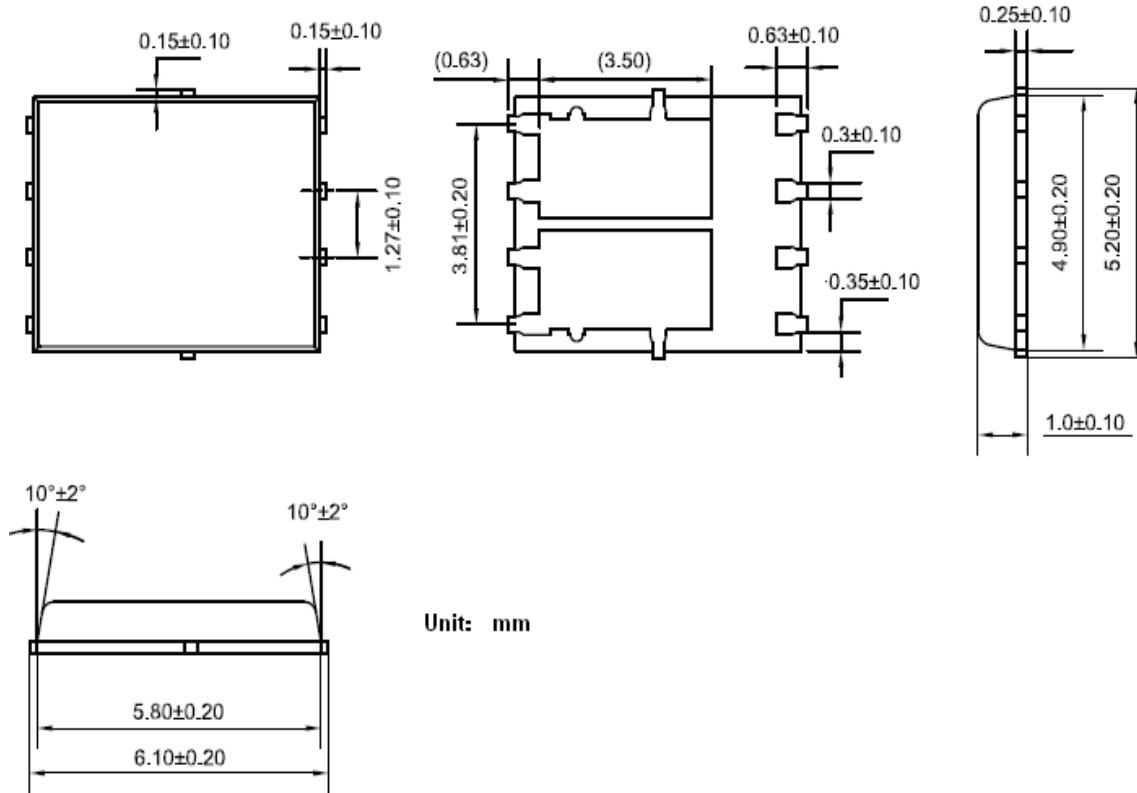


Fig11. Switching Time Test Circuit and waveforms

Dual DFN5x6 Package Outline



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